

ABSTRACT OF THE DISCLOSURE

A no-clean soldering flux consists essentially of one or more halide-free, water soluble activators in an aggregate amount not exceeding about 5% by weight of the flux, a water soluble fluorinated surfactant in an amount not exceeding about 1% by weight of the flux, and water. The flux is substantially VOC-free and is particularly useful in a method of producing soldered printed wiring assemblies with minimal residual ionic contamination, so that post-soldering cleaning of the assemblies is unnecessary. The absence of significant amounts of VOC's and the elimination of post-soldering cleaning result in substantial environmental and production-related benefits.

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This Sheet Has Been Replaced

